L Number	Hits	Search Text	DB	Time stamp
1	10	frit with lithograph$7	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 14:12
-	62	frit with "125"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 14:11
-	2	frit with linewidth	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 13:35
-	281	frit with width	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 13:35
-	99	(frit with width) same seal$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 13:35
-	135	(frit with width) same (bond$4 or seal$4 or adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 13:35
-	13	((frit with width) same (bond$4 or seal$4 or adhesive)) same (microns or micrometers or ".mu." or mu or micron or micrometer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/06 13:36

C:\APPS\east\workspaces\10017942 bond cap wafer to base wafer saw.wsp

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      (FILE 'HOME' ENTERED AT 14:17:23 ON 06 APR 2004)

      FILE 'CAPLUS, INSPEC, JICST-EPLUS' ENTERED AT 14:17:43 ON 06 APR 2004
L1           1 S FRIT AND LINEWIDTH
L2          58 S FRIT AND PHOTOLITHOGRAPH?
L3          29 S FRIT AND LITHOGRAPH?
L4          53 S FRIT AND PHOTORESIST
L5         117 S L2 OR L3 OR L4
L6         114 DUPLICATE REMOVE L5 (3 DUPLICATES REMOVED)
L7           1 S L6 AND (MEMS OR SENSOR OR ACTUATOR OR ACOUSTIC OR SAW OR TRA
L8          24 S L6 AND (SEAL? OR BOND?)

=> s l6 and (micron)
L9           1 L6 AND (MICRON)
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